

Connector for CompactFlash™

SCFB Series



Unique eject mechanism achieves high operability and 5mm ejection stroke.

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

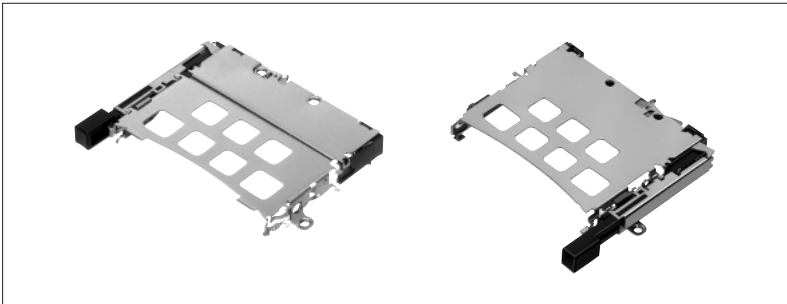
For
Memory
Stick Micro™

For
Memory
Stick™

Combine Type

For
Compact
Flash™

For CMOS
Camera Module



Typical Specifications

Items		Specifications
		Type II compatible
Structure	Pin pitch	1.27mm
	Numbers of pins	50pins
	Applicable media	Type I , Type II
	Media ejection	5mm
	Mounting type	Surface mounting type
	Mounting style	Standard mount/ Reverse mount
	Ejection mechanism	2 step
	Stand-off	0/1.2mm
Performance	Operating temperature range	−20℃ to +60℃
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Insertion and removal cycle	10,000cycles

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Position of knob	Applicable card	Product No.		Drawing No.
					Pin header	Ejector	
2 step lever ejection type	Standard mount	0	Right	Type I/Type II	SCFB1A0500	SCFB3A0300	1
			Left			SCFB3A0900	2
		1.2	Right		SCFB1A0900	SCFB3A0200	3
			Left			SCFB3A1000	4
	Reverse mount	0	Right		SCFB1A0600	SCFB3A0400	5
			Left			SCFB3A0500	6

Note

Pin headers and ejectors are supplied as separate parts. To apply these parts, solder the pin header to the printed circuit board, assemble the ejector to the pin header and screw cramp.

Packing Specifications

Bulk

Product No.	Number of packages (pcs.)		Export package measurements (mm)
	1 case /Japan	1 case /export packing	
SCFB1A0500	540	2,160	482×336×271
SCFB1A0600			
SCFB1A0900			
SCFB3A0200	400	800	519×379×263
SCFB3A0300			
SCFB3A0400			
SCFB3A0500			
SCFB3A0900			
SCFB3A1000			

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	2 step Standard type Stand-off 0mm Position of knob: Right	
2	2 step Standard type Stand-off 0mm Position of knob: Left	

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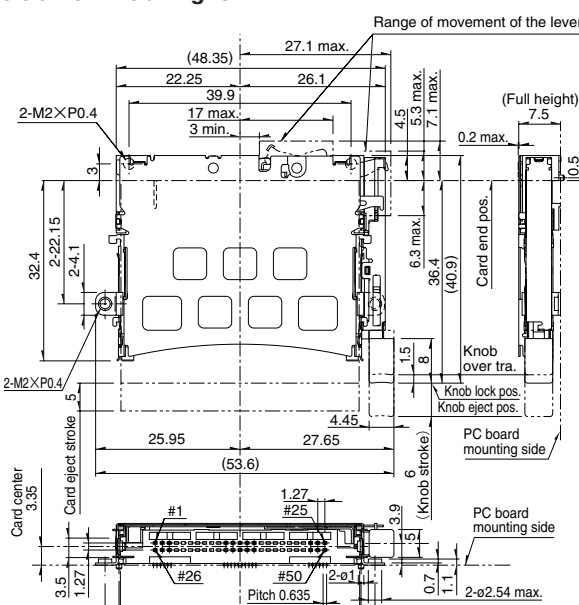
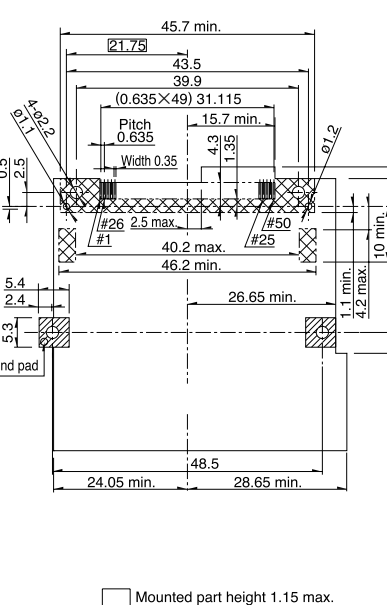
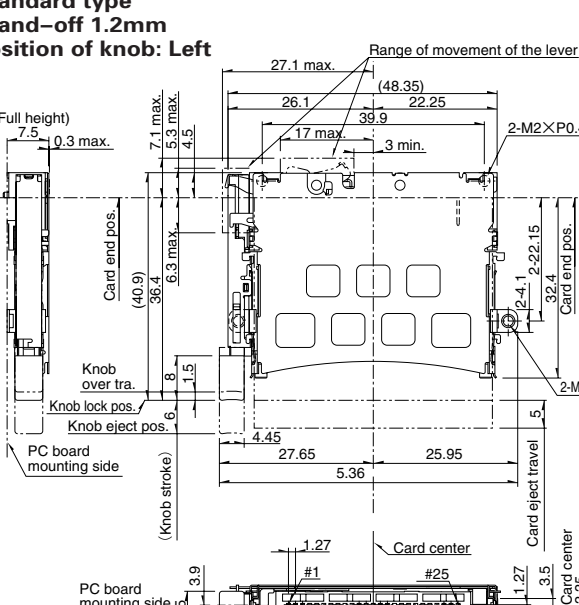
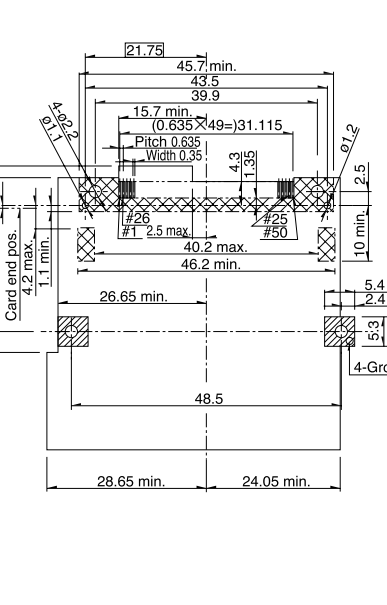
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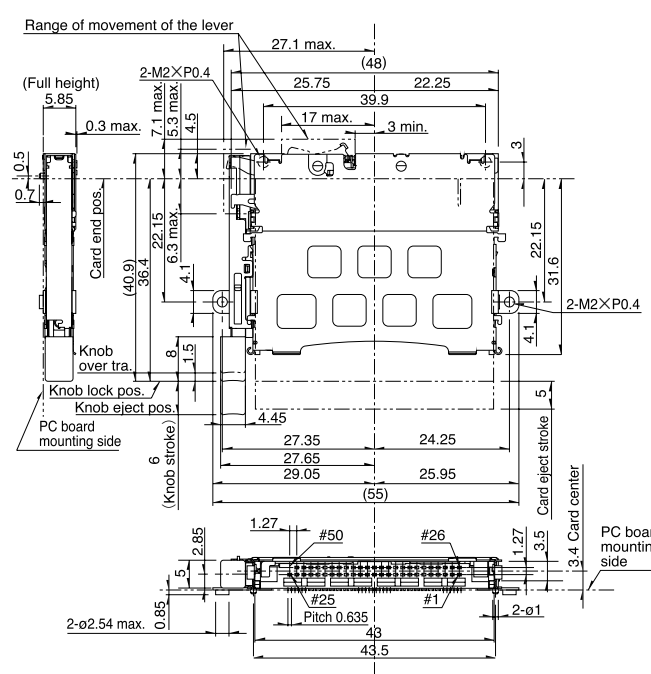
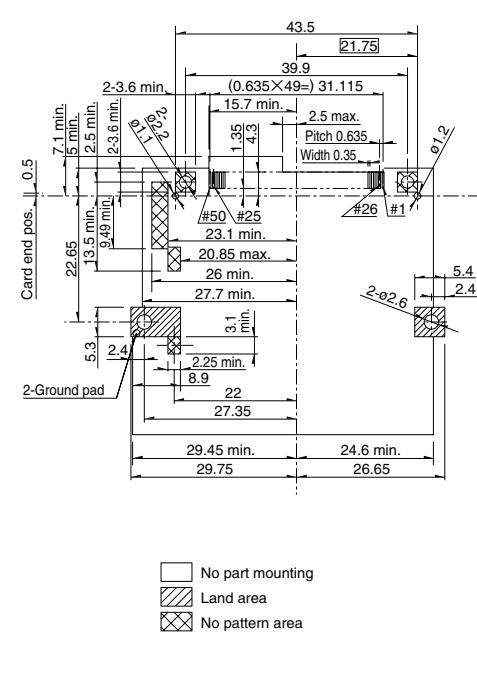
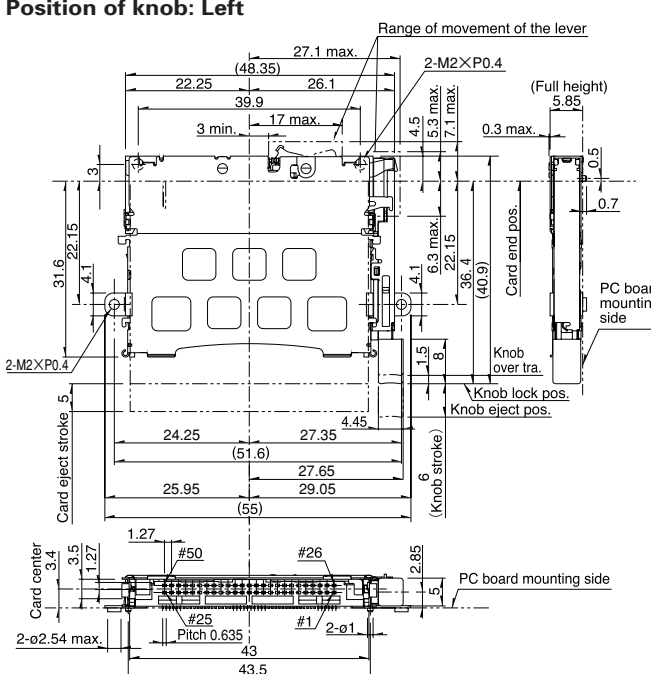
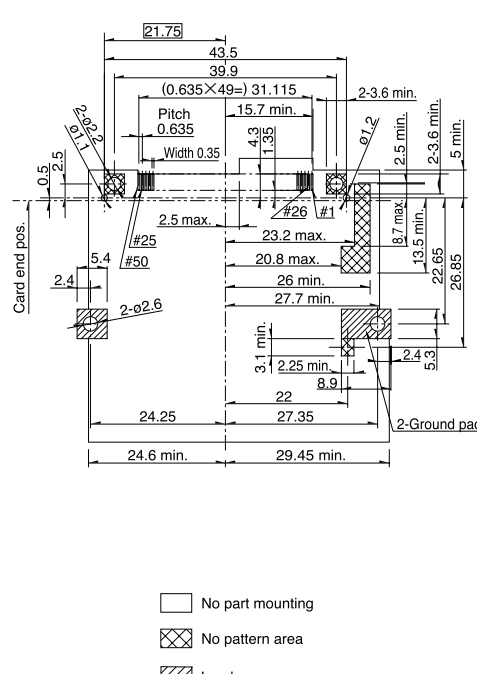
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No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
3	2 step Standard type Stand-off 1.2mm Position of knob: Right 	 ☐ Mounted part height 1.15 max. ☒ No part mounting ☒ Land area
4	2 step Standard type Stand-off 1.2mm Position of knob: Left 	 ☐ Mounted part height 1.15 max. ☒ No part mounting ☒ Land area

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
5	2 step Reverse type Stand-off 0mm Position of knob: Right 	
6	2 step Reverse type Stand-off 0mm Position of knob: Left 	

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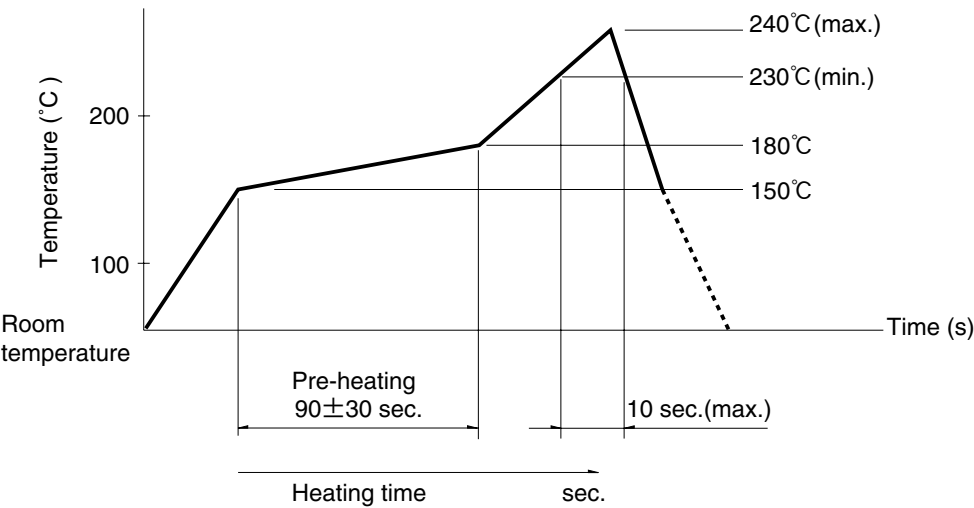
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products) .



Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.